MOSFETs Silicon N-channel MOS (U-MOSIV)

TPCP8011

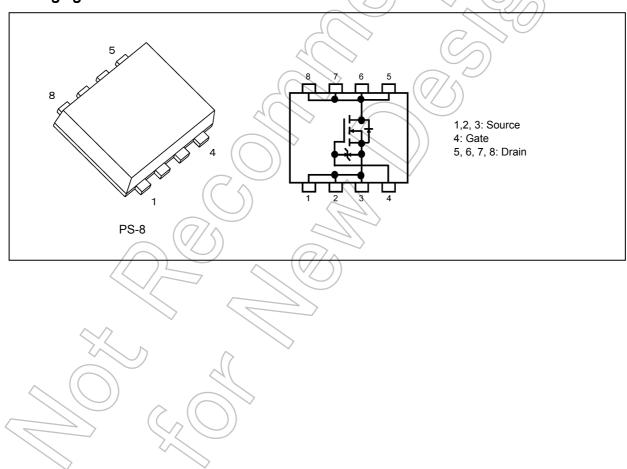
1. Applications

- Motor Drivers
- Mobile Equipment

2. Features

- (1) AEC-Q101 qualified
- (2) Small, thin package
- (3) Small gate charge : $Q_{SW} = 4.7 \text{ nC}$ (typ.)
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 25.5 \text{ m}\Omega \text{ (typ.)} (V_{GS} = 10 \text{ V})$
- (5) Low leakage current: $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 40 \ V)$
- (6) Enhancement mode: $V_{th} = 2$ to 3 V ($V_{DS} = 10$ V, $I_D = 1$ mA).

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25^{\circ}C$ unless otherwise specified)

| Characteristics | | | Symbol | Rating | Unit |
|-------------------------------|-----------|----------|---------------------|------------|------|
| Drain-source voltage | | | V _{DSS} | 40 | V |
| Gate-source voltage | | | V _{GSS} | ±20 | |
| Drain current (DC) | | (Note 1) | I _D | 5 | A |
| Drain current (pulsed) | | (Note 1) | I _{DP} | 20 | |
| Power dissipation | (t = 5 s) | (Note 2) | PD | 1.96 | W |
| Power dissipation | (t = 5 s) | (Note 3) | PD | 0.94 | W |
| Single-pulse avalanche energy | | (Note 4) | EAS | 33.2 | mJ |
| Avalanche current | | | IAR |) 5 | A |
| Channel temperature | | (Note 5) | Tch | 175 | °C |
| Storage temperature | | (Note 5) | (T _{stg}) | -55 to 175 |] |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

| CI | naracteristics | $(\bigcirc/ \le$ | Symbol | Max | Unit |
|---------------------------------------|----------------|------------------|-----------------------|-------|------|
| Channel-to-ambient thermal resistance | (t = 5 s) | (Note 2) | R _{th(ch-a)} | 76.5 | °C/W |
| Channel-to-ambient thermal resistance | (t = 5 s) | (Note 3) | R _{th(ch-a)} | 159.5 | °C/W |
| | | | () | | |

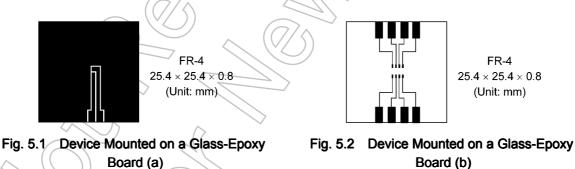
Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4: V_{DD} = 25 V, T_{ch} = 25°C (initial), L = 1.379 mH, R_G = 1 Ω , I_{AR} = 5 A

Note 5: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.



Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

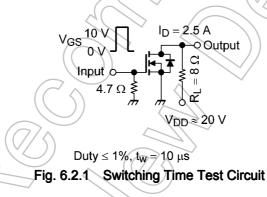
6. Electrical Characteristics

6.1. Static Characteristics (Ta = 25°C unless otherwise specified)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--------------------------------|----------------------|---|---------------|------|------|------|
| Gate leakage current | I _{GSS} | V_{GS} = ±16 V, V_{DS} = 0 V | _ | _ | ±10 | μA |
| Drain cut-off current | I _{DSS} | V _{DS} = 40 V, V _{GS} = 0 V | Y | _ | 10 | |
| Drain-source breakdown voltage | V _{(BR)DSS} | I _D = 10 mA, V _{GS} = 0 V | 40 | | — | V |
| Drain-source breakdown voltage | V _{(BR)DSX} | I _D = 10 mA, V _{GS} = -20 V | 20 | (| _ | |
| Gate threshold voltage | V _{th} | V _{DS} = 10 V, I _D = 1 mA | 2 | 2.5 | 3 | |
| Drain-source on-resistance | R _{DS(ON)} | V _{GS} = 6 V, I _D = 2.5 A | γ | 32 | 51.2 | mΩ |
| | | V _{GS} = 10 V, I _D = 2.5 A | \mathcal{T} | 25.5 | 31.8 | |

6.2. Dynamic Characteristics ($T_a = 25^{\circ}C$ unless otherwise specified)

| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|--------------------------------|------------------|--|----------|------|-----|------|
| Input capacitance | C _{iss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | - (| 505 | | pF |
| Reverse transfer capacitance | C _{rss} | | ((| 66 | _ | |
| Output capacitance | C _{oss} | | K | 115 |) — | |
| Switching time (rise time) | t _r | See Figure 6.2.1 | \sim | 5.37 | — | ns |
| Switching time (turn-on time) | t _{on} | | | 12 | — | |
| Switching time (fall time) | t _f | | ~_) | 4.34 | — | |
| Switching time (turn-off time) | t _{off} | | <u> </u> | 17.4 | _ | |



6.3. Gate Charge Characteristics ($T_a = 25^{\circ}$ C unless otherwise specified)

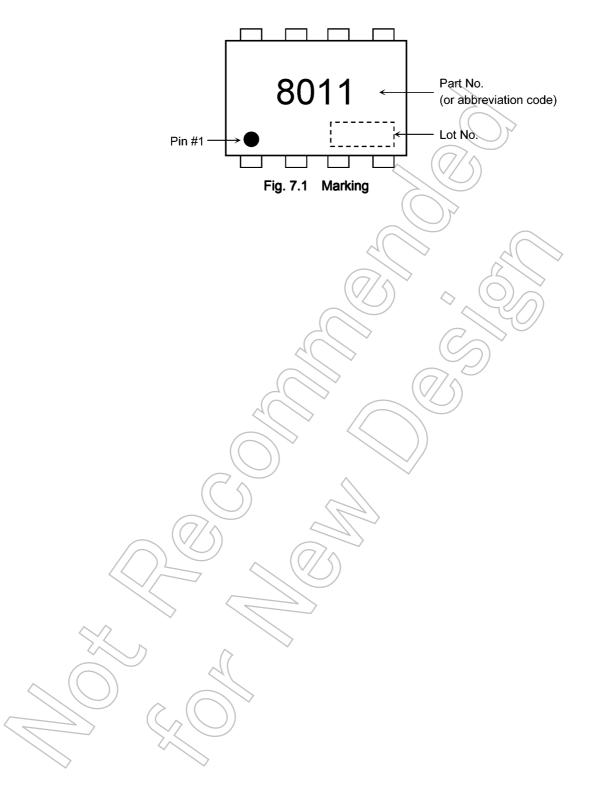
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|---|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | Qg | $V_{DD} \approx 32$ V, V_{GS} = 10 V, I_D = 5 A | _ | 11.8 | — | nC |
| Gate-source charge 1 | Q _{gs1} | | _ | 2.1 | _ | |
| Gate-drain charge | Q _{gd} | | _ | 3.9 | _ | |
| Gate switch charge | Q _{SW} | | _ | 4.7 | _ | |

6.4. Source-Drain Characteristics ($T_a = 25^{\circ}C$ unless otherwise specified)

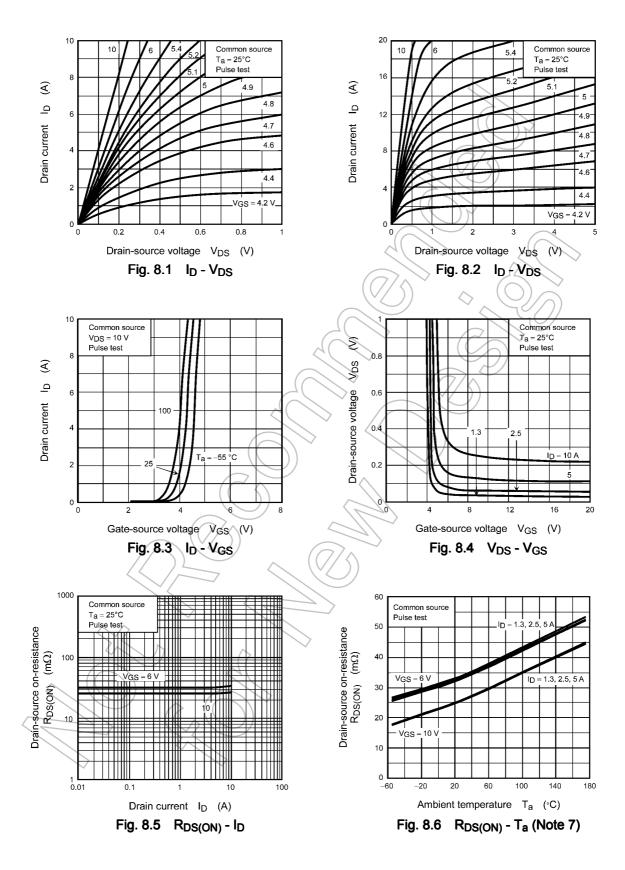
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|--|-----|------|------|------|
| Reverse drain current (pulsed) (Note 6) | I _{DRP} | — | _ | — | 20 | А |
| Diode forward voltage | V _{DSF} | I _{DR} = 5 A, V _{GS} = 0 V | | | -1.2 | V |

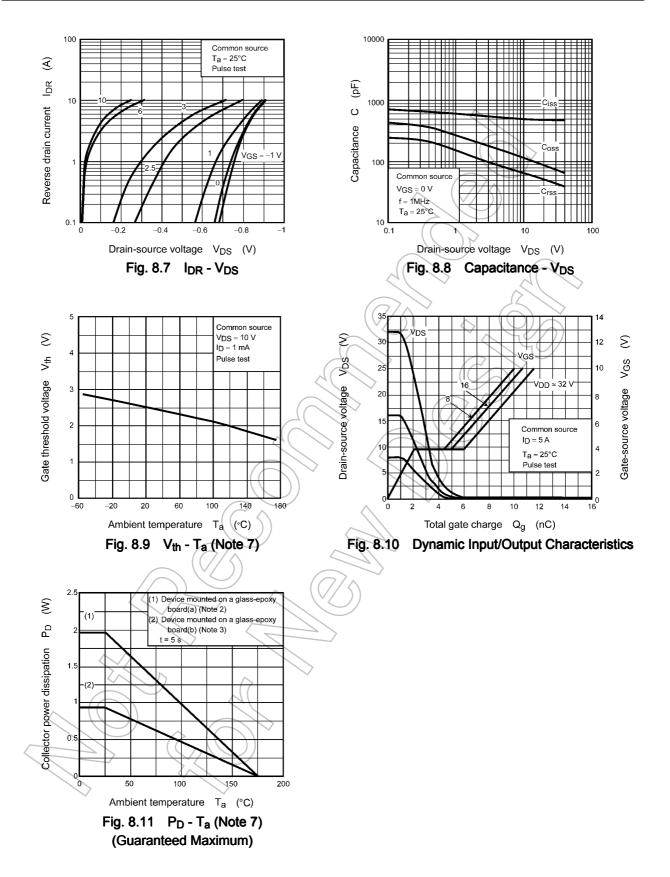
Note 6: Ensure that the channel temperature does not exceed 175°C.

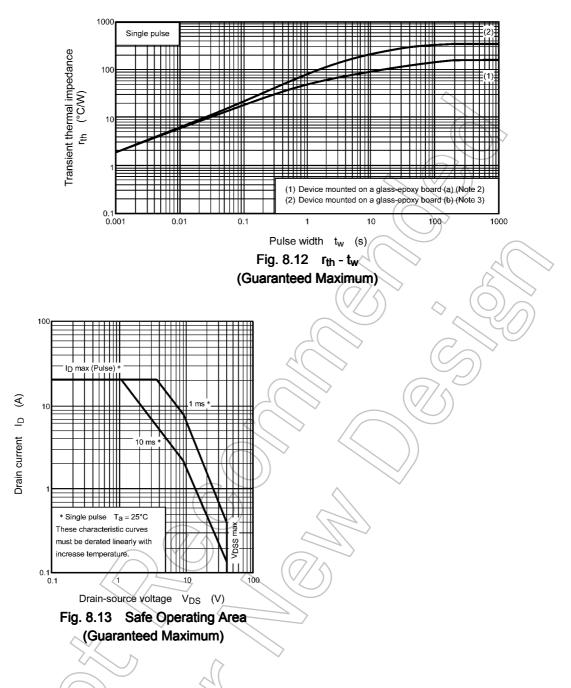
7. Marking



8. Characteristics Curves (Note)





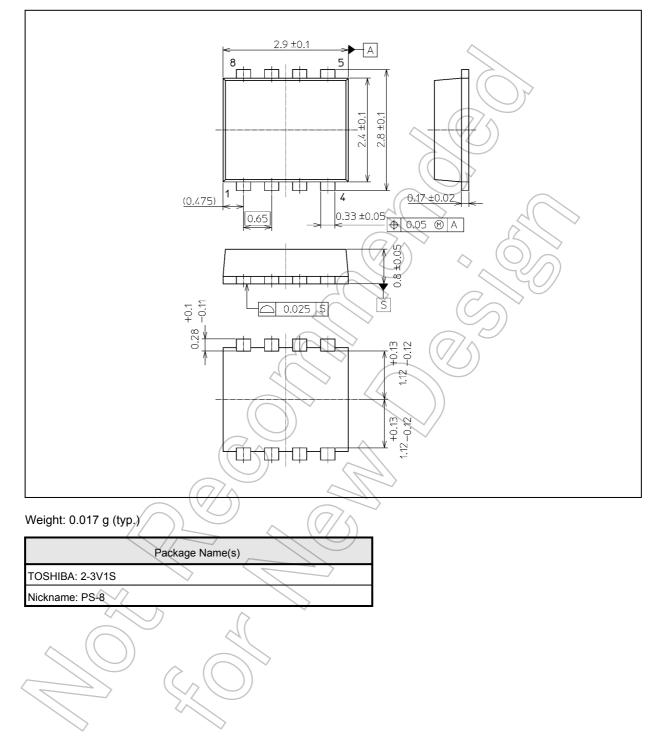


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Note 7: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

Package Dimensions

Unit: mm



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